



PIN ASSIGNMENT MATRIX

	1	2
A	V _{CC}	GND
B	SCL	SDA

COMMON DIMENSIONS
(Unit of Measure = mm)

SYMBOL	MIN	TYP	MAX	NOTE
A	0.260	0.295	0.330	
A1	0.080	0.095	0.110	
A2	0.160	0.175	0.190	
A3	0.025 REF			3
D	Contact Microchip for details			
d1	0.400 BSC			
E	Contact Microchip for details			
e1	0.400 BSC			
b	0.170	0.185	0.200	

- Note: 1. Dimensions are NOT to scale.
 2. Solder ball composition is 95.5Sn-4.0Ag-0.5Cu.
 3. Product offered with Back Side Coating (BSC)

5/6/15

TITLE

4U-11, 4-ball, 2x2 Array, 0.40mm Pitch
 Wafer Level Chip Scale Package (WLCSP) with BSC

GPC

GTM

DRAWING NO.

4U-11

REV.

A